INTEGRATED CIRCUITS



Product specification Supersedes data of 1995 Mar 20 File under Integrated Circuits, IC02 1996 Jun 06



TDA5630BT

FEATURES

- Balanced mixer with a common emitter input for band A (single input)
- 2-pin oscillator for band A
- Balanced mixer with a common base input for band C
- 3-pin oscillator for band C
- · Local oscillator buffer output for external prescaler
- SAW filter preamplifier with a low output impedance to drive a SAW filter
- · Band gap voltage stabilizer for oscillator stability
- Electronic band switch.

APPLICATIONS

- Cable tuners for TV and VCR (switched concept for VHF)
- Recommended RF bands for Europe: 48.25 to 105.25 MHz, 112.25 to 294.25 MHz and 471.25 to 855.25 MHz
- Recommended RF bands for the USA: 55.25 to 133.25 MHz, 139.25 to 361.25 MHz and 367.25 to 801.25 MHz.

GENERAL DESCRIPTION

The TDA5630BT is a monolithic integrated circuit that performs VHF and UHF mixer/oscillator functions in TV and VCR cable tuners. With a proper oscillator application and by using a switchable inductor to split the VHF band into two sub-bands, the full VHF/UHF TV bands can be covered. This low-power mixer/oscillator requires a power supply of 9 V and is available in a very small package.

The device gives the designer the capability to design an economical and physically small cable tuner.

The tuner development time can be drastically reduced by using this device.

Frequency bands are determined by the external tank circuit. They can be adapted to various standards.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
VP	supply voltage		_	9.0	-	V
I _P	supply current		-	48	-	mA
f _{RF}	frequency range (picture carrier)	RF input; band A; note 1	45	-	470	MHz
		RF input; band C; note 1	430	_	860	MHz
G _v	voltage gain	band A	_	25	-	dB
		band C	_	36	-	dB
NF	noise figure	band A	-	7.5	-	dB
		band C	_	9.0	-	dB
Vo	output voltage to get 1% cross	band A	-	118	-	dBµV
	modulation in channel	band C	_	120	-	dBμV

Note

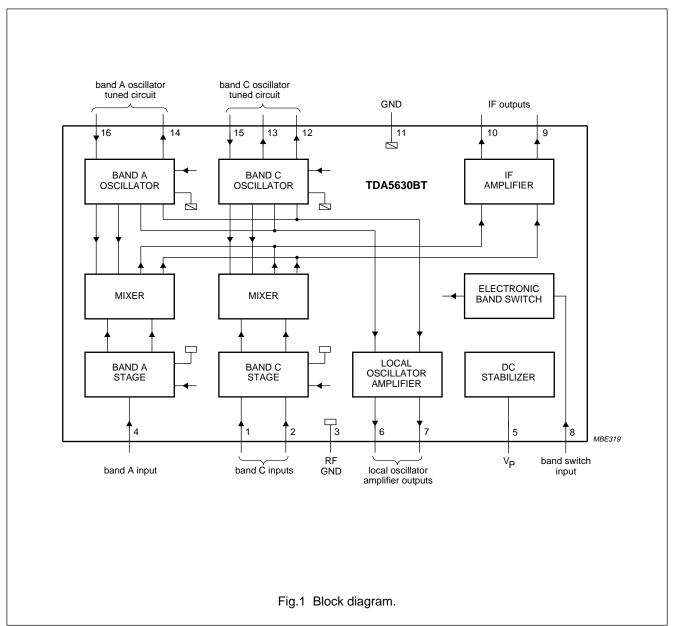
1. The limits are related to the tank circuits used in Fig.11 and the intermediate frequency. Frequency bands may be adjusted by the choice of external components.

ORDERING INFORMATION

TYPE	PACKAGE		
NUMBER	NAME	DESCRIPTION	VERSION
TDA5630BT	SO16	plastic small outline package; 16 leads; body width 3.9 mm	SOT109-1

QUICK REFERENCE DATA

BLOCK DIAGRAM

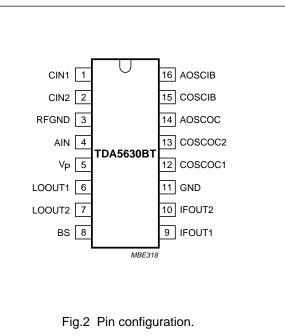


TDA5630BT

9 V VHF and UHF mixer/oscillator for TV and VCR cable tuners

PINNING

SYMBOL	PIN	DESCRIPTION
CIN1	1	band C input 1
CIN2	2	band C input 2
RFGND	3	ground for RF inputs
AIN	4	band A input
V _P	5	supply voltage
LOOUT1	6	local oscillator amplifier output 1
LOOUT2	7	local oscillator amplifier output 2
BS	8	band switch input
IFOUT1	9	IF amplifier output 1
IFOUT2	10	IF amplifier output 2
GND	11	ground (0 V)
COSCOC1	12	band C oscillator output collector 1
COSCOC2	13	band C oscillator output collector 2
AOSCOC	14	band A oscillator output collector
COSCIB	15	band C oscillator input base
AOSCIB	16	band A oscillator input base



LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	MIN.	MAX.	UNIT
VP	supply voltage	-0.3	+10.5	V
V _{SW}	switching voltage	0	10.5	V
lo	output current of each pin referenced to ground	-	-10	mA
t _{s(max)}	maximum short-circuit time (all pins)	-	10	S
T _{stg}	IC storage temperature	-55	+150	°C
T _{amb}	operating ambient temperature	-10	+70	°C
Tj	junction temperature	-	150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
R _{th j-a}	thermal resistance from junction to ambient in free air	115	K/W

HANDLING

Human body model: the IC withstands 2000 V in accordance with the UZW-B0/FQ-A302 specification equivalent to the MIL-STD-883C category B (2000 V)

(stress reference pins RFGND, GND and V_P short-circuited together).

Machine model: the IC withstands 200 V in accordance with the UZW-B0/FQ-B302 specification (issue date: Nov 6th, 1990)

(stress reference pins RFGND, GND and V_{P} short-circuited together).

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CHARACTERISTICS

 V_{P} = 9 V; T_{amb} = 25 °C; measured in circuit of Fig.11; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply			1		1	1
V _P	supply voltage		8.1	9.0	9.9	V
I _P	supply current		35	48	55	mA
V _{SW}	switching voltage	band A	0	_	1.1	V
		band C	3.0	_	5.0	V
I _{SW}	switching current	band A	-	-	2	μA
		band C	-	-	10	μA
Band A m	ixer including IF amplifier					
f _{RF}	frequency range	note 1; V _t = 0.45 to 28 V	45	-	300	MHz
f _{max}	maximum frequency	note 1	-	470	_	MHz
G _v	voltage gain	f _{RF} = 50 MHz; see Fig.3; note 2	22.5	25	27.5	dB
		f _{RF} = 300 MHz; see Fig.3; note 2	22.5	25	27.5	dB
		f _{RF} = 470 MHz; see Fig.3; note 2	_	25	-	dB
NF	noise figure	f _{RF} = 50 MHz; see Figs 4 and 5	-	7.5	8.5	dB
	f _{RF} = 180 MHz; see Figs 4 and 5	-	9	10	dB	
	f _{RF} = 300 MHz; see Fig.5	-	10.5	11.5	dB	
Vo	output voltage	causing 1% cross modulation in channel; f _{RF} = 300 MHz; see Fig.6	115	118	-	dBμV
Vi	input voltage	causing 10 kHz pulling in channel; f _{RF} = 300 MHz; note 3	-	104	-	dBμV
g _{os}	optimum source	f _{RF} = 50 MHz	_	0.5	_	mS
	conductance for noise figure	f _{RF} = 180 MHz	_	1.1	_	mS
gi	input conductance	f _{RF} = 50 MHz; see Fig.12; note 4	_	0.26	_	mS
		f _{RF} = 180 MHz; see Fig.12; note 4	-	0.35	_	mS
Ci	input capacitance	f _{RF} = 50 to 180 MHz; see Fig.12; note 4	-	2	-	pF
Band A os	scillator					
f _{osc}	frequency range	note 5; $V_t = 0.45$ to 28 V	80	_	336	MHz
f _{shift}	frequency shift	$\Delta V_{P} = 10\%$; note 6	_	_	200	kHz
f _{drift}	frequency drift	$\Delta T = 25$ °C with no compensation; NP0 capacitors; note 7	-	-	500	kHz
		5 s to 15 min after switch on; with no compensation; NP0 capacitors; note 8	-	500	950	kHz
		5 s to 15 min after switch on; with compensation; note 9	-	200	300	kHz

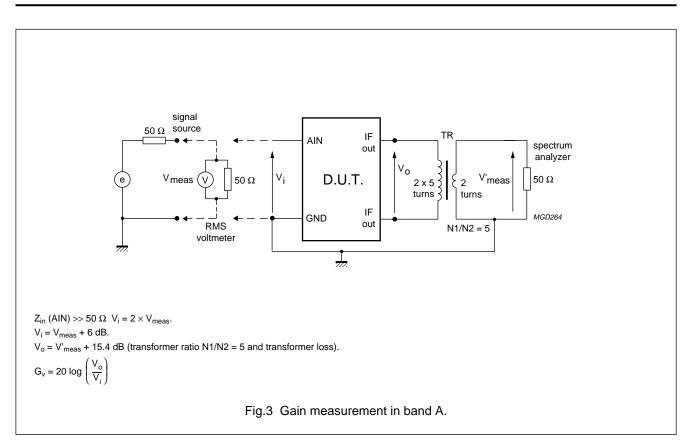
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Band C m	ixer including IF amplifier; m	easurements using hybrid; note 10		1		4
f _{RF}	frequency range	V _t = 0.45 to 28 V; note 1	430	_	860	MHz
G _v voltage gain		f _{RF} = 430 MHz; see Fig.7; note 2	33	36	39	dB
		f _{RF} = 860 MHz; see Fig.7; note 2	33	36	39	dB
NF	noise figure	not corrected for image				
		f _{RF} = 430 MHz; see Fig.8	-	9	10	dB
		f _{RF} = 860 MHz; see Fig.8	_	11	12	dB
Vo	output voltage	causing 1% cross modulation in channel				
		f _{RF} = 430 MHz; see Fig.9	116	120	_	dBµV
		f _{RF} = 860 MHz; see Fig.9	116	120	_	dBµV
Vi	input voltage	causing 10 kHz pulling in channel; f _{RF} = 860 MHz; note 3	-	84	-	dBμV
		causing N + 5 - 1 MHz pulling; f _{RF} = 820 MHz; see Fig.10	-	63	-	dBμV
Zi	input impedance ($R_S + jL_S\omega$)	R _S at f _{RF} = 430 MHz; see Fig.13; note 4	-	40	_	Ω
		R _S at f _{RF} = 860 MHz; see Fig.13; note 4	_	53	-	Ω
		L_S at f_{RF} = 430 to 860 MHz; see Fig.13; note 4	-	9	-	nH
Band C os	scillator	1		1		1
f _{osc}	frequency range	note 5; $V_t = 0.45$ to 28 V	470	_	900	MHz
f _{shift}	frequency shift	$\Delta V_{P} = 10\%$; note 6	_	_	400	kHz
f _{drift}	frequency drift	$\Delta T = 25$ °C with no compensation; NP0 capacitors; note 7	-	-	2.5	MHz
		5 s to 15 min after switch on; with no compensation; NP0 capacitors; note 8	-	1000	1300	kHz
		5 s to 15 min after switch on; with compensation; note 9	-	550	950	kHz
IF amplifie	er	•				
s ₂₂	output reflection coefficient	magnitude; see Fig.14; note 4	-	-10	-	dB
		phase; see Fig.14; note 4	-	9	_	0
Zo	output impedance	R _S ; see Fig.14; note 4	-	95	-	Ω
	$(R_{S} + jL_{S}\omega)$	L _s ; see Fig.14; note 4	_	45	_	nH

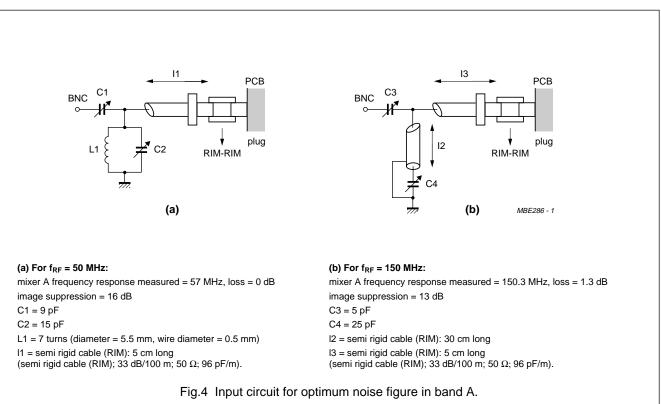
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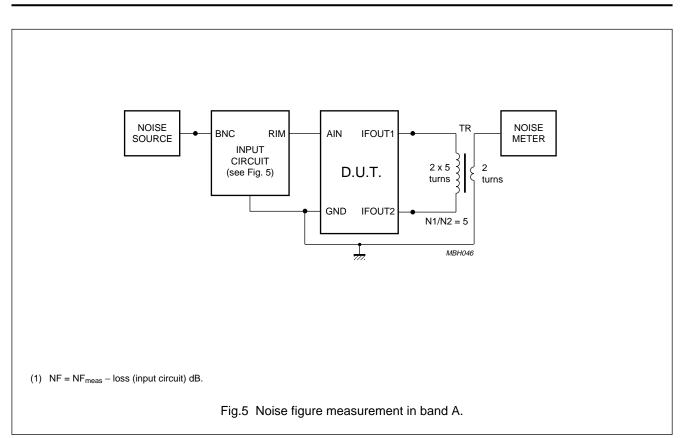
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
LO output	; R _L = 100 Ω					
Y _o	output admittance	f _{osc} = 80 MHz; see Fig.15; note 4	-	2.5	-	mS
	(G _P + jC _P ω)		-	0.9	-	pF
		f _{osc} = 900 MHz; see Fig.15; note 4	-	3.5	-	mS
			-	0.7	-	pF
Vo	output voltage	$R_L = 100 \ \Omega; V_t = 0.45 \text{ to } 28 \text{ V}$	83	91	100	dBµV
SRF	spurious signal on LO output with respect to LO output signal	note 11	-	-	-10	dBc
SHD	LO signal harmonics with respect to LO signal		_	-	-10	dBc

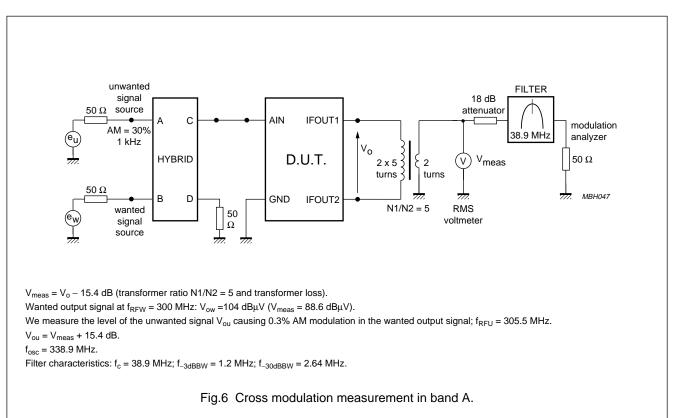
Notes to the characteristics

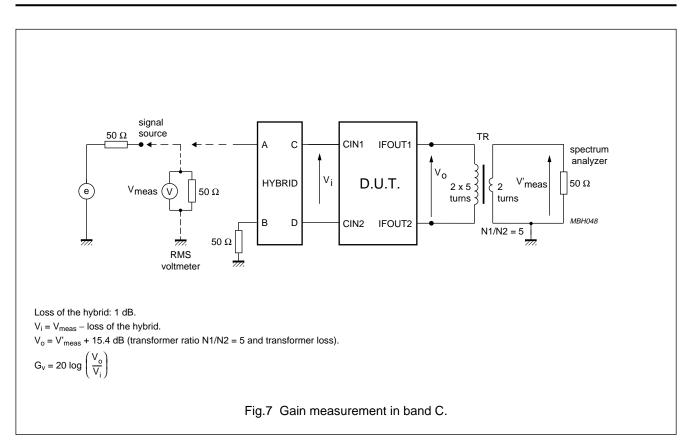
- 1. The RF frequency range is defined by the oscillator frequency range and the intermediate frequency.
- 2. The gain is defined as the transducer gain (measured in Fig.11) plus the voltage transformation ratio of L6 to L7 (10 : 2, 15.4 dB including transformer loss).
- 3. The input level causing 10 kHz frequency detuning at the LO output. $f_{osc} = f_{RF} + 33.4$ MHz.
- 4. All s-parameters are referred to a 50 Ω system.
- 5. Limits are related to the tank circuits used in Fig.11. Frequency bands may be adjusted by the choice of external components.
- 6. The frequency shift is defined as the change in oscillator frequency when the supply voltage varies from $V_P = 9$ to 8.1 V or from $V_P = 9$ to 9.9 V.
- 7. The frequency drift is defined as the change in oscillator frequency when the ambient temperature varies from T_{amb} = 25 to 0 °C or from 25 to 50 °C. With no compensation, all capacitors are NP0.
- 8. Switch on drift with no compensation is defined as the change of oscillator frequency between 5 s and 15 min after switch on. All capacitors are NP0.
- 9. Switch on drift with compensation is defined as the change of oscillator frequency between 5 s and 15 min after switch on. C5 to C11 are N750; C1, C2 and C4 are N470.
- 10. The values have been corrected for hybrid and cable losses. The symmetrical output impedance of the hybrid is 100 Ω .
- 11. Measured with RF input voltage:
 - a) RF voltage = 120 dB μ V at f_{RF} < 180 MHz.
 - b) RF voltage = 107.5 dB μ V at 180 MHz < f_{RF} < 225 MHz.
 - c) RF voltage = 97 dB μ V at 225 MHz < f_{RF} < 860 MHz.

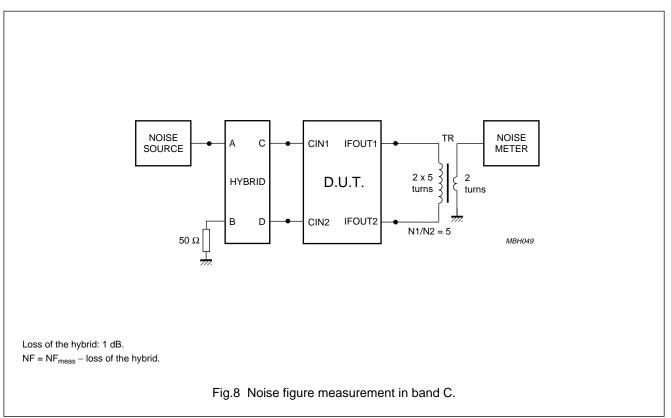


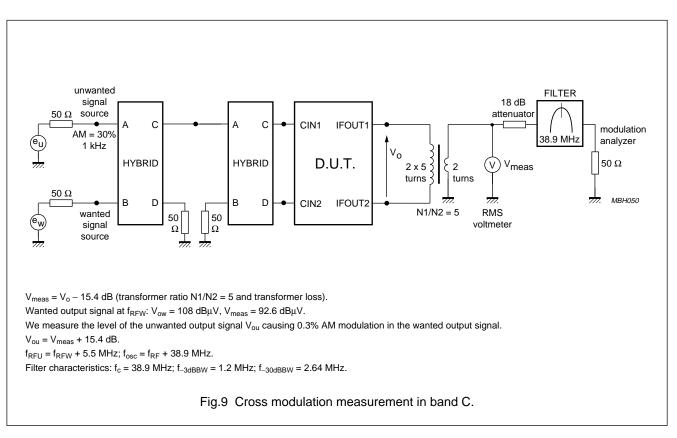


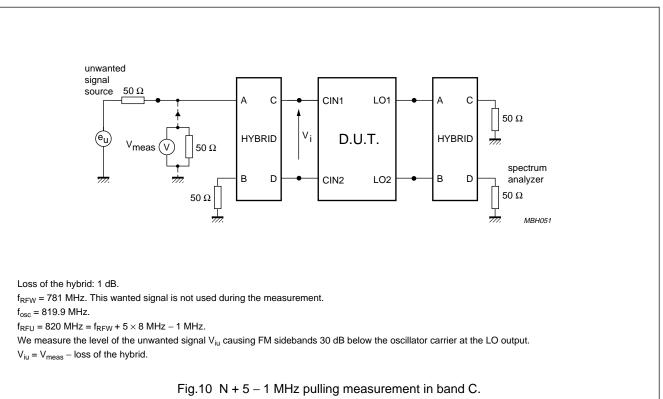


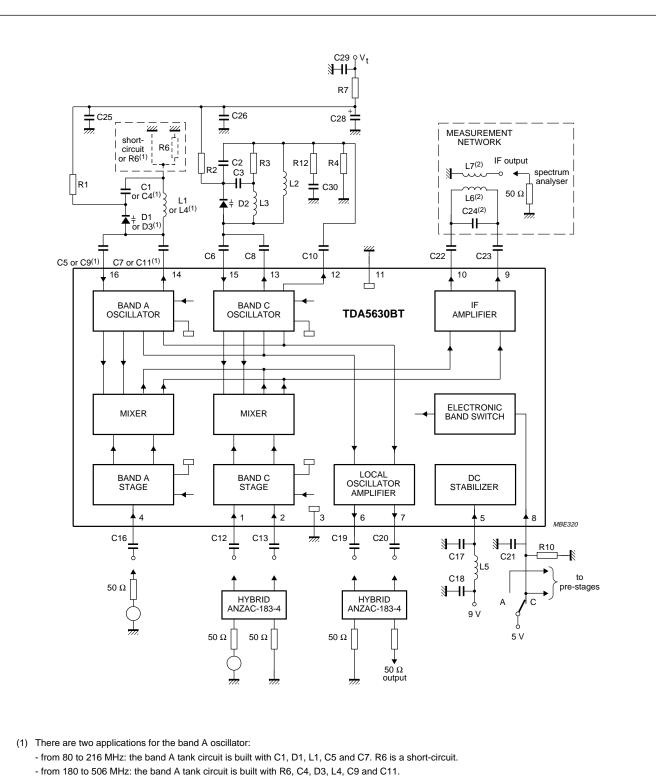












- from 180 to 506 MHZ: the band A tank circuit is built with R6, C4, D3, L4, C9 and C11.

(2) L6, L7 and C24 are only required for measurement purposes; they are not used in a tuner.

Fig.11 Measurement circuit.

Component values for measurement circuit

Table 1 Capacitors (all SMD and NP0 except C28)

COMPONENT	VALUE
C1	82 pF
C2	5.6 pF
C3	100 pF
C4	150 pF
C5	2.2 pF
C6	1 pF
C7	2.2 pF
C8	1 pF
C9	1.8 pF
C10	2.2 pF
C11	3.9 pF
C12	1 nF
C13	1 nF
C16	1 nF
C17	1.5 nF
C18	1.5 nF
C19	1 nF
C20	1 nF
C21	1.5 nF
C22	1 nF
C23	1 nF
C24	18 pF
C25	1.5 nF
C26	1.5 nF
C28	1 µF; 40 V electrolytic
C29	1.5 nF
C30	0.56 pF

Table 2Resistors (all SMD)

COMPONENT	VALUE
R1	47 kΩ
R2	22 kΩ
R3	2.2 kΩ
R4	22 kΩ
R6	22 Ω
R7	1 kΩ
R12	470 Ω

Table 3 Diodes and IC

COMPONENT	VALUE
D1	BB911
D2	BB405 or BB215
D3	BB909 or BB219
IC	TDA5630BT

Table 4 Coils (wire size 0.4 mm)

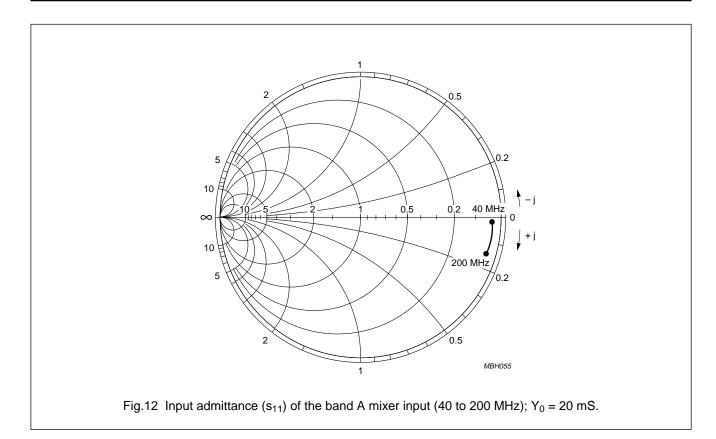
COMPONENT	VALUE
L1	7.5 turns; diameter 3 mm
L2	2.5 turns; diameter 3 mm
L3	1.5 turns; diameter 2.5 mm
L4	1.5 turns; diameter 4 mm
L5	4.7 μH; choke coil

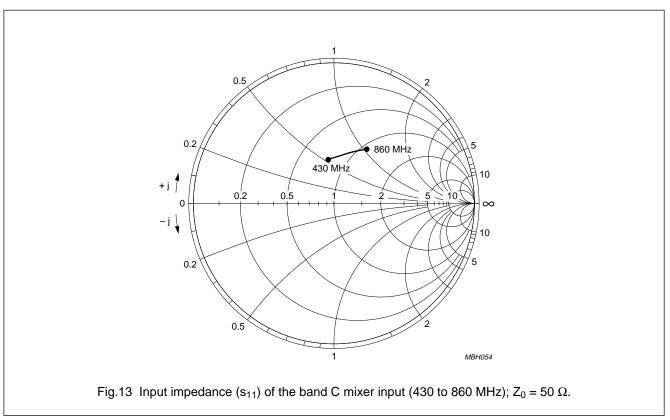
Table 5 Transformers; note 1

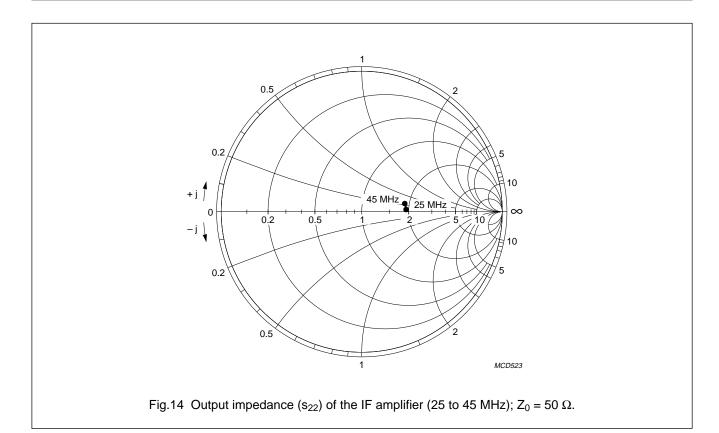
COMPONENT	VALUE	
L6	2×5 turns	
L7	2 turns	

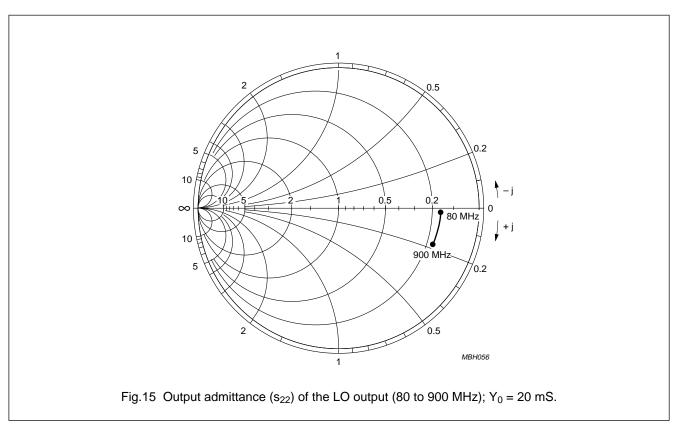
Note

1. Coil type: TOKO 7 kN; material: 113 kN; screw core 03-0093; pot core 04-0026.









TDA5630BT

INTERNAL PIN CONFIGURATION

SYMBOL PIN	PIN	DESCRIPTION	AVERAGE DC VOLTAGE IN (V) measured in circuit of Fig.11	
			BAND A	BAND C
CIN1	1		NR ⁽¹⁾	2.2
CIN2	2		NR ⁽¹⁾	2.2
RFGND	3	MGD605 777.	0.0	0.0
AIN	4		2.2	NR ⁽¹⁾
VP	5	supply voltage	9.0	9.0
LOOUT1	6		7.3	7.3
LOOUT2	7		7.3	7.3
BS	8	(8) (1) (1) (1) (1) (1) (1) (1) (1) (1) (1	0.0	5.0

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SYMBOL PIN	PIN	DESCRIPTION	AVERAGE DC VOLTAGE IN (V) measured in circuit of Fig.11	
		BAND A	BAND C	
IFOUT1	9		4.0	4.0
IFOUT2	10	9	4.0	4.0
GND	11	MGD610 (11)	0	0
COSCOC1	12		NR ⁽¹⁾	4.4
COSCOC2	13		NR ⁽¹⁾	4.4
COSCIB	15		NR ⁽¹⁾	2.3
AOSCOC	14		4.0	NR ⁽¹⁾
AOSCIB	16		2.2	NR ⁽¹⁾

Note

1. NR = not relevant.

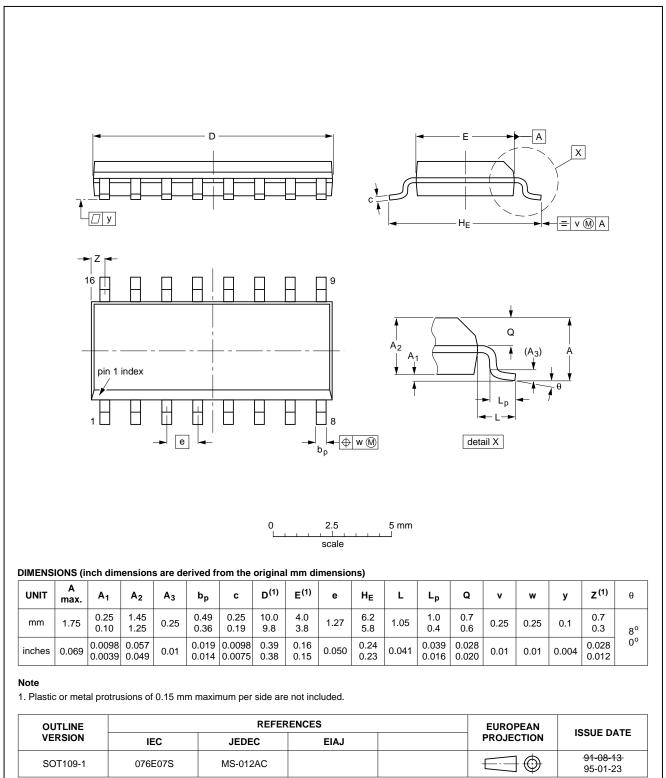
Product specification

TDA5630BT

9 V VHF and UHF mixer/oscillator for TV and VCR cable tuners

PACKAGE OUTLINE

SO16: plastic small outline package; 16 leads; body width 3.9 mm



SOT109-1

SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our *"IC Package Databook"* (order code 9398 652 90011).

Reflow soldering

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

Wave soldering

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Repairing soldered joints

Fix the component by first soldering two diagonallyopposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

TDA5630BT

DEFINITIONS

Data sheet status		
Objective specification	This data sheet contains target or goal specifications for product development.	
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.	
Product specification	This data sheet contains final product specifications.	
Limiting values		
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.		
Application information		

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.